

System On Package: Miniaturization Of The Entire System By Rao Tummala

By Rao Tummala

miniaturization [min ch r z sh n] (electronics) Reduction in the size and weight of a system, package, or component by using small parts arranged

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Then, the improvement of the miniaturization technique, the integration of the new antenna in a full System in Package (SiP) and its measurement is demonstrated.

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Xpeedic s SiP design service enables customers to achieve system miniaturization by integrating ICs from different process into one package.

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